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## U.S. PATENT DOCUMENTS

Examiner Initial	Document Number							Date	Name	Class	Subclass	Filing Date if Appropriate
	4	5	2	5	6	3	1					
AD	5	6	7	1	8	5	1	9/1997	Johnson et al.	211	51	
	5	7	3	8	8	0	0	4/1998	Hosali et al.	216	99	
	5	7	5	9	9	1	7	6/1998	Grover et al.	438	690	
	6	0	1	9	8	0	6	2/2000	Sees et al.	51	308	
	6	0	4	2	7	4	1	3/2000	Hosali et al.	252	79.1	
	6	1	1	4	2	4	9	9/2000	Canaperi et al.	438	692	
	6	1	3	2	6	3	7	10/2000	Hosali et al.	252	79.1	
	6	2	1	8	3	0	5	4/2001	Hosali et al.	438	691	
AD	6	2	3	8	4	9	4	5/2001	Segal	148	421	
AD	6	4	1	0	4	4	4	6/2002	Kido et al.	438	693	

## FOREIGN PATENT DOCUMENTS

	Document Number	Date	Country	Class	Subclass	Translation	
						Yes	No

## Other Documents (including Author, Title, Date, Pertinent Pages, Etc.)

AD		Cook, "Chemical Processes in Glass Polishing", Journal of Non-Crystalline Solids (1990) pp 152-171
		Lo et al, "Characterization of Selective-CMP, Dummy Pattern and Reverse Mask Approaches in STI Planarization Process", Proceedings of 1999 CMP-MIC, pp-333-335
		Lee et al., "The Effects of Slurries with Pattern Size and Step Height in Shallow Trench Isolation Chemical Mechanical Polishing", Proceedings of 2000 CMP-MIC, pp 288-290
		Jin et al., "Advanced Front End CMP and Integration Solutions", Proceedings of 2000 CMP-MIC, pp 119-129
		Bonner et al., "Development of a Direct Polish Process for Shallow Trench Isolation Modules", Proceedings of 2001 CMP-MIC, pp. 572-579
AD		Xiao, "Introduction to Semiconductor Manufacturing Technology", Prentice-Hall Inc. (2001) pp. 384

Examiner	Anthony Ojini	Date Considered	2/7/05
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